

Electronic Patent Application Fee Transmittal

Application Number:	10598124
Filing Date:	18-Aug-2006
Title of Invention:	Solder composition and method of bump formation therewith
First Named Inventor/Applicant Name:	Isao Sakamoto
Filer:	Stephen M. Roylance/Timothy BOONE
Attorney Docket Number:	P30245

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				940